

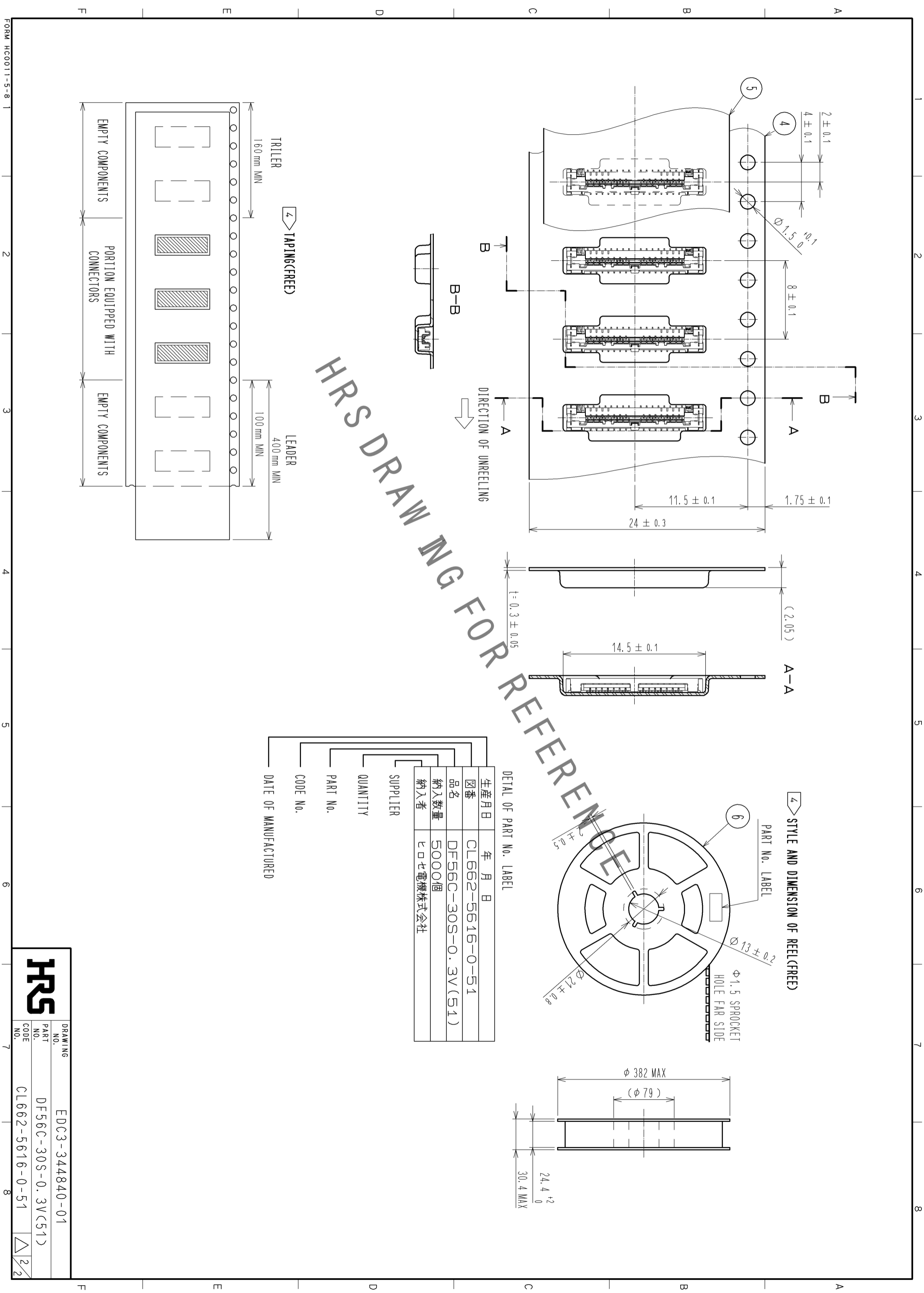
NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mmMAX.
 2. PER REEL : 5000 COMPONENTS.
 3. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
 4. REFER TO JIS 0806. (PACKING OF COMPONENTS FOR AUTO HANDLING)
 5. DO NOT MOUNT ANY OTHER COMPONENTS TO THE INDICATED AREA WHEN USING OUR RECOMMENDED TOOL.
 6. LOCATION OF THE CONNECTOR AND RECOMMENDED PCB LAYOUT ARE ALIGNED WITH THOSE CENTERS.

RECOMMENDED METAL MASK
 THICKNESS 0.1mm
 OPENING RATIO 100% (LEAD PAD)
 100% (GND PAD)

NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
1	PHOSPHOR BRONZE	LEAD AREA : Au PLATING 0.1 μ mMIN UNDER PLATING : Ni PLATING 1 μ mMIN	3	PHOSPHOR BRONZE	WHOLE AREA : Sn PLATING 1 μ mMIN UNDER PLATING:Cu PLATING 0.3 μ mMIN
2	LCP	UL94V-0. BLACK	4	PS	CLEAR
			5	POLYESTER	CLEAR
			6	PS	BLACK

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	FREE					

APPROVED	CHECKED	DESIGNED	DRAWN
TS. SAKATA	HS. OZAWA	TP. MATSUMOTO	TP. MATSUMOTO
12.06.12	12.06.12	12.06.12	12.06.12
EDC3-344840-01	DF56C-30S-0.3V(51)	CL662-5616-0-51	



HRS DRAWING FOR REFERENCE

DETAIL OF PART NO. LABEL

生産月日	年月日
図番	CL662-5616-0-51
品名	DF56C-30S-0.3V(51)
納入数量	5000個
納入者	ヒロセ電機株式会社
SUPPLIER	
QUANTITY	
PART No.	
CODE No.	
DATE OF MANUFACTURED	

HRS	DRAWING NO.	EDC3-344840-01
	PART NO.	DF56C-30S-0.3V(51)
	CODE NO.	CL662-5616-0-51

FORM HC0011-5-8